

SOT117-2

plastic dual in-line package; 28 leads (600 mil); long body

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DIP28
Package type industry code	DIP28
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	051G06
JEDEC package outline code	MS-011
JEITA package outline code	SC-510-28
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	35.94	-	36.51	37.08	mm
E	package width	13.84	-	14.03	14.22	mm
A	seated height	[tbd]	-	5.08	5.08	mm
A ₂	package height	[tbd]	-	3.94	3.94	mm
n ₂	actual quantity of termination	-	-	28	-	



2. Package outline

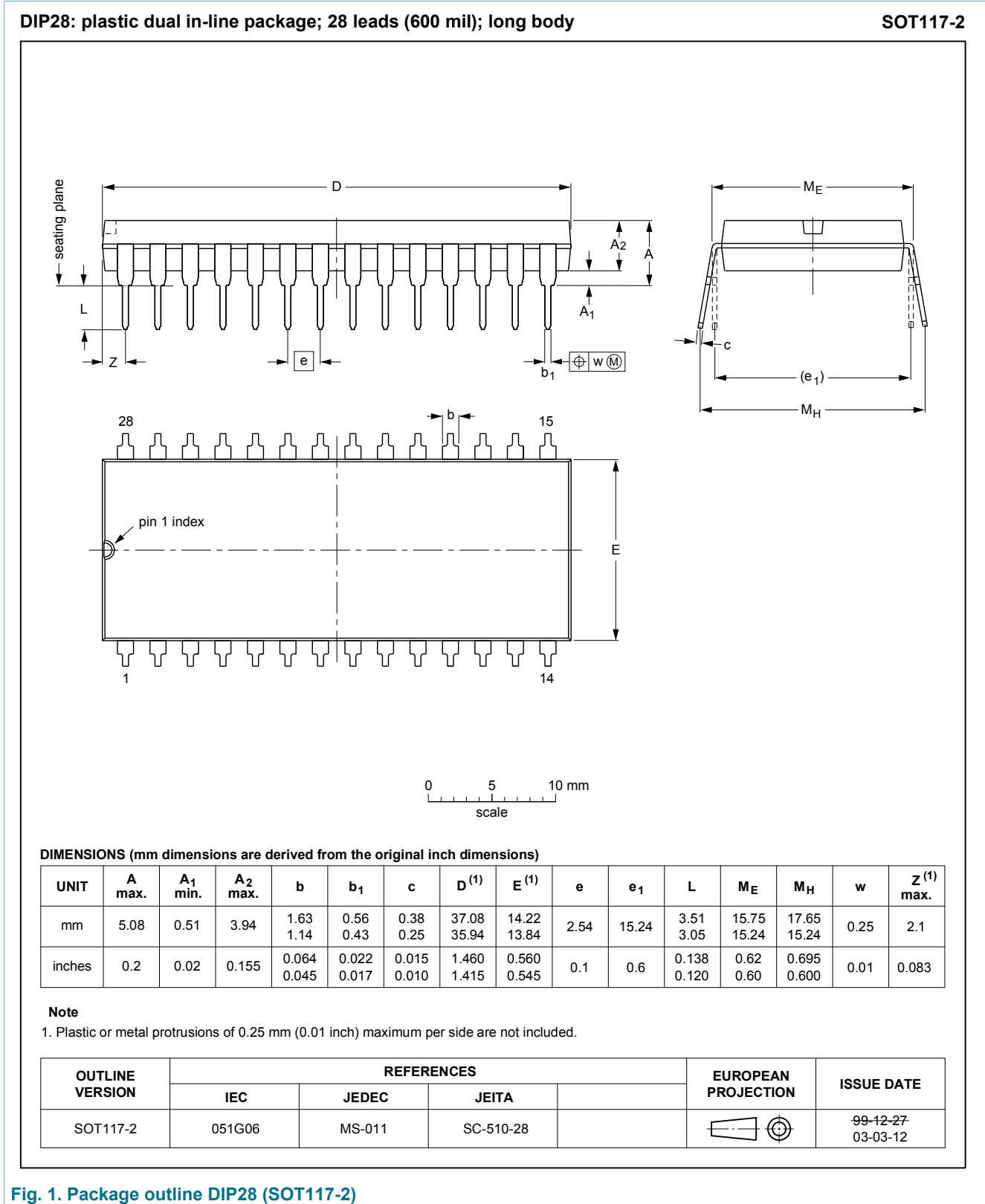


Fig. 1. Package outline DIP28 (SOT117-2)

3. Legal information

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